

Application No. 10/643,043
Docket No. DP-308286
Amendment dated September 27, 2005
Reply to Office Action of July 27, 2005

Amendments to the Specification:

Please replace paragraph [0011] with the following amended paragraph:

[0011] Figure 2 is a cross-sectional view of a non-overmolded package containing flip chip ~~a flip chip~~ devices mounted to a substrate, with a heat-conductive member contacting the topside of each device.